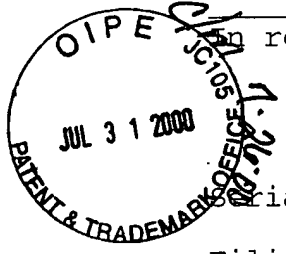


#7/Amend B
8.8.00
C. Willis

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



re application of:

TONGBI JIANG
EDWARD SCHROCK

Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: March 1, 1999

Examiner: PAREKH, N.

Title: BGA PACKAGE HAVING SUBSTRATE WITH
PATTERNED SOLDER MASK DEFINING OPEN
DIE ATTACH AREA (AS AMENDED)

Attorney Docket No.: 98-0645.1

AMENDMENT
July 26, 2000

Assistant Commissioner of Patents
BOX AMENDMENT (FEE)
Washington, D.C. 20231

Sir:

This Amendment is in response to the Office Action dated April 26, 2000 having a statutory period for response set to expire on July 26, 2000. Please amend the captioned case as follows.

In the Specification

Please change the title to --BGA Package Having Substrate With Patterned Solder Mask Defining Open Die Attach Area--.

In the "Cross Reference to Related Applications" added by the Preliminary Amendment dated March 1, 1999 after "1998" add --, now U.S. Patent No. 6,048,755--.

On page 11, line 25, after "die 16.", add /-The die attach opening 86 defines the die attach area 50 on the substrate 56.-/.

B1

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